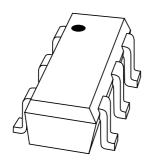
### **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# PUMF12 PNP general purpose transistor; NPN resistor-equipped transistor

**Product specification** 

2002 Nov 07





# PNP general purpose transistor; NPN resistor-equipped transistor

#### PUMF12

#### **FEATURES**

- General purpose transistor and resistor equipped transistor in one package
- 100 mA collector current
- 50 V collector-emitter voltage
- 300 mW total power dissipation
- SOT363 package; replaces two SOT323 (SC-70) packaged devices on same PCB area
- · Reduced pick and place costs.

#### **APPLICATIONS**

- Power management switch for portable equipment,
   e.g. cellular phone and CD player
- · Switch for regulator.

#### **DESCRIPTION**

PNP general purpose transistor and an NPN resistor-equipped transistor in a SOT363 (SC-88) plastic package.

#### **MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>	
PUMF12	R2*	

#### Note

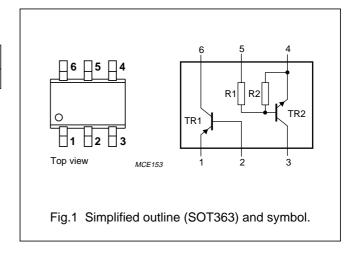
- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT			
TR1 (PNP)	TR1 (PNP)					
V <sub>CEO</sub>	collector-emitter voltage	-50	V			
I <sub>C</sub>	collector current (DC) -100 n		mA			
I <sub>CM</sub>	peak collector current	-200	mA			
TR2 (NPN)						
V <sub>CEO</sub>	collector-emitter voltage	50	V			
Io	output current (DC)	100	mA			
R1	bias resistor 22 kΩ		kΩ			
R2	bias resistor 47 k $\Omega$		kΩ			

#### **PINNING**

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	



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#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per transistor						
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	200	mW	
T <sub>stg</sub>	storage temperature range		-65	+150	°C	
Tj	junction temperature		_	150	°C	
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C	
TR1 (PNP)						
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V	
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-40	V	
V <sub>EBO</sub>	emitter-base voltage open collector		_	-5	V	
I <sub>C</sub>	collector current (DC)		_	-100	mA	
I <sub>CM</sub>	peak collector current		_	-200	mA	
TR2 (NPN)		·	·			
V <sub>CBO</sub>	collector-base voltage	open emitter	_	50	V	
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V	
V <sub>EBO</sub>	emitter-base voltage open collector		_	10	V	
Vi	input voltage					
	positive		_	+40	V	
	negative		_	-10	V	
Io	output current (DC)		_	100	mA	
I <sub>CM</sub>	peak collector current		_	100	mA	
Per device			_			
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	300	mW	

#### Note

1. Device mounted on an FR4 printed-circuit board.

#### THERMAL CHARACTERISTICS

SYMBO	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	416	K/W

#### Note

1. Device mounted on an FR4 printed-circuit board.

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#### **CHARACTERISTICS**

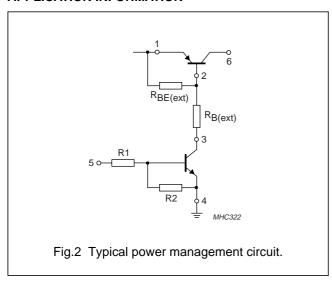
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
TR1 (PNP)	TR1 (PNP)					
I <sub>CBO</sub>	collector cut-off current	$V_{CB} = -30 \text{ V}; I_{E} = 0$	_	-	-100	nA
		$V_{CB} = -30 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-10	μΑ
I <sub>EBO</sub>	emitter cut-off current	$V_{EB} = -4 \text{ V}; I_{C} = 0$	_	_	-100	nA
V <sub>CEsat</sub>	saturation voltage	$I_C = -50 \text{ mA}$ ; $I_B = -5 \text{ mA}$ ; note 1	_	-	-200	mV
h <sub>FE</sub>	DC current gain	$V_{CE} = -6 \text{ V}; I_{C} = -1 \text{ mA}$	120	-	-	
C <sub>c</sub>	collector capacitance	$V_{CB} = -12 \text{ V}; I_E = i_e = 0; f = 1 \text{ MHz}$	_	_	2.2	pF
f <sub>T</sub>	transition frequency	$V_{CE} = -12 \text{ V}; I_{C} = -2 \text{ mA}; f = 100 \text{ MHz}$	100	-	-	MHz
TR2 (NPN)						
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0	_	_	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0; T_{j} = 150 ^{\circ}\text{C}$	_	-	50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0	_	_	120	μΑ
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 5 mA	80	_	_	
V <sub>CEsat</sub>	saturation voltage	I <sub>C</sub> = 10 mA; I <sub>B</sub> = 0.5 mA	_	-	150	mV
V <sub>i(off)</sub>	input off voltage	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 100 μA	_	0.9	0.5	V
V <sub>i(on)</sub>	input on voltage	V <sub>CE</sub> = 0.3 V; I <sub>C</sub> = 2 mA	2	1.1	_	V
R1	input resistor		15.4	22	28.6	kΩ
R2 R1	resistor ratio		1.7	2.1	2.6	
C <sub>c</sub>	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0; f = 1 \text{ MHz}$	_	_	2.5	pF

#### Note

1. Device mounted on an FR4 printed-circuit board.

#### **APPLICATION INFORMATION**



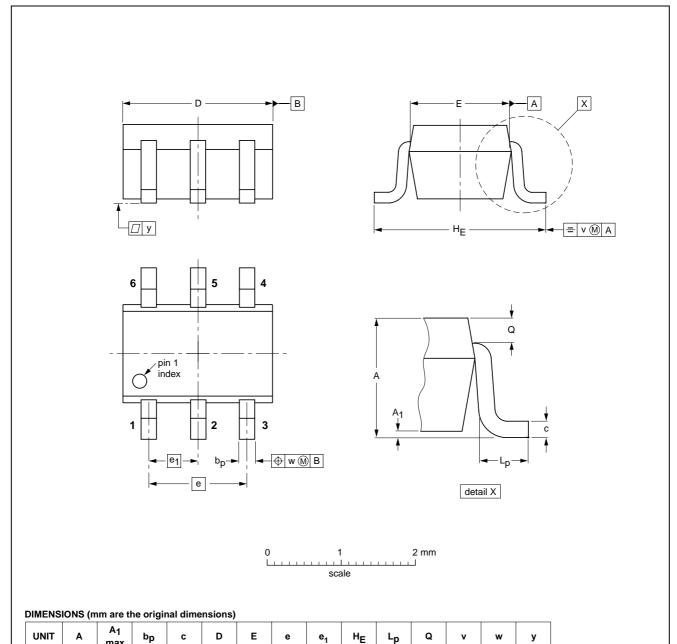
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#### **PACKAGE OUTLINE**

Plastic surface mounted package; 6 leads

**SOT363** 



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION ISSUE DA	
SOT363			SC-88			97-02-28

0.65

0.45 0.15 0.25 0.15

0.2

0.1

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0.30

0.20

0.25

0.10

1.1 0.8

mm

0.1

2.2 1.8 1.35 1.15

1.3

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#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
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**NOTES** 

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